

Surface Mount Schottky Diode

This device is an extremely fast Schottky diode housed in the ultra-small SOD-323 package.

FEATURES

- Ultra low Vf
- · Low capacitance for reduced insertion loesses
- · Reverse voltage rating of 30V
- · Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

APPLICATIONS

- · Mobile phones and accessories
- · Hand-held computers
- · High speed switching applications

MECHANICAL DATA

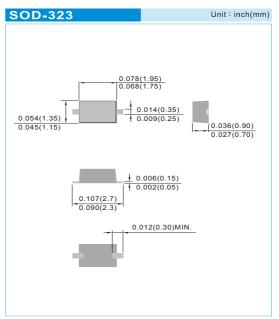
· Case: SOD-323, Plastic

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.0041 grams

• Marking Code: 551





MAXIMUM RATINGS TJ=25°C unless otherwise noted

Rating	Symbol	Value	Units
Peak Reverse Voltage I _R =500μA	V _{RM}	30	V
Continuous Reverse Voltage	V _R	20	V
Average Rectified Forward Current	I _{F(AV)}	500	mA
Non-repetitive Peak Forward Current, 60Hz Half Sine-Wave	I _{FSM}	5	Α
Total Power Dissipation (Note1)	Ртот	200	mW
Operating Junction Temperature Range	T _J	-55 to + 125	°C
Storage Temperature Range	T _{STG}	-55 to + 150	°C

Note 1. FR-5 Board 1 x 0.75 x 0.062 in.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Units
Thermal Resistance, Junction to Ambient	$R_{\scriptscriptstyle{\Theta}JA}$	500	°C/W

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ELECTRICAL CHARACTERISTICS TJ=25°C unless otherwise noted

Parameter	Symbol	Conditions	Min	Тур	Max	Units
Forward Voltage (Note 2)	V_{F}	I _F =100mA I _F =500mA	-	-	0.36 0.47	V
Reverse Leakage Current	I _R	V _R =20V	-	-	100	μΑ
Total C apacitance	Ст	0Vdc Bias, f = 1MHz 10Vdc Bias, f = 1MHz	-	-	85 20	pF

Note 2. Short duration pulse test to avoid self-heating effect

TYPICAL CHARACTERISTIC CURVES

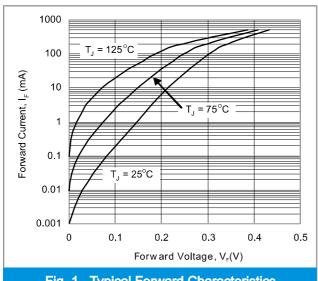


Fig. 1. Typical Forward Characteristics

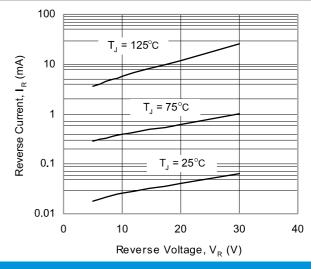
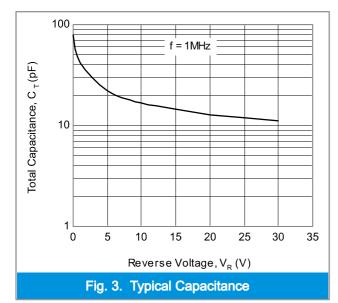


Fig. 2. Typical Reverse Characteristics



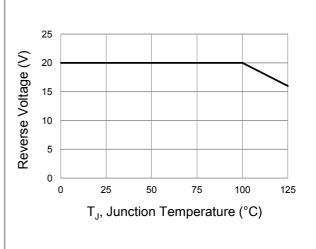


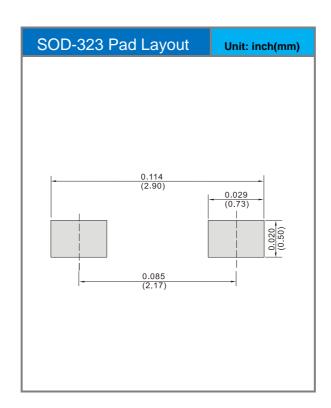
Fig. 4. Operating Temperature Derating Curve



Product and Packing Information

Part No.	Package Type	Packing Type	Marking
RB551V-30	SOD-323	5K pcs / 7" reel	551
RB551V-30	SOD-323	12K pcs / 13" reel	551

Mounting Pad Layout





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